

# Final Program



# ISQED

2019

20<sup>th</sup> International Symposium on

## QUALITY ELECTRONIC DESIGN

March 6-7, 2019

Santa Clara Convention Center,  
Santa Clara, CA USA

International Society for Quality Electronic Design  
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**Security, IoT, ML/AI &  
Electronic Design**



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# WELCOME TO ISQED 2019

On behalf of the ISQED 2019 conference and technical committees, we are pleased to welcome you to the 20<sup>th</sup> anniversary of the International Symposium on Quality Electronic Design.

ISQED is the premier interdisciplinary and multidisciplinary electronic design conference aimed at bridging the gap among electronic/semiconductor ecosystem members and providing electronic design tools, integrated circuit techniques, semiconductor manufacturing, advanced 3D integration, and assembly and test methodologies to achieve the overall design quality.

ISQED 2019 is held with the technical sponsorship of the IEEE Electron Devices Society, the IEEE Circuits and Systems Society, and the IEEE Reliability Society. All Conference proceedings & Papers have been published in IEEE Xplore digital library and indexed by Scopus. ISQED continues to provide and foster a unique opportunity to participants to interact and engage themselves in cutting edge tutorials, presentations, and panel and plenary sessions.

This conference is organized around the theme “Security, IoT, ML/AI & Electronic Design”. We have invited distinguished keynote speakers, tutorial speakers and panelists who will focus on these timely topics.

The two-day technical program with three parallel sessions packs over 50 peer-reviewed papers highlighting the latest trends in electronic circuit and system design & automation, testing, verification, sensors, security, semiconductor technologies, cyber-physical systems, etc. ISQED 2019 also features a panel discussion, entitled “Hype or hope: Is machine learning the next generation of design and design automation?” on Wednesday, March 6<sup>th</sup>.

All of the technical presentations, plenary sessions, panel discussions, tutorials and related events will take place on March 6-7 at the Santa Clara Convention Center in Santa Clara, CA USA.

We would like to thank the ISQED corporate sponsors: Synopsys, and Mentor Graphics, for their valuable support of this conference. Welcome to another exciting year of ISQED! It couldn't have happened without your support and participation.

#### **General Chair**

**Brian T. Cline**  
ARM

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**Kurt Schwartz**  
Texas Instruments

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**Peng Li**  
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Texas Instruments

#### **Special Sessions Chair**

**Vinod Viswanath**  
Real Intent

#### **Publication Chair**

**Paul Wesling**  
IEEE

#### **TPC Chair**

**Swaroop Ghosh**  
Pennsylvania State University

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**José Pineda de Gyvez**  
Eindhoven University of technology

#### **Panel Co-Chair**

**Li-C Wang**  
University of California, Santa Barbara

#### **Special Sessions Co-Chair**

**Abhilash Goyal**  
Oracle

#### **Plenary Chair**

**Ali A. Iranmanesh**  
Silicon Valley Polytechnic Inst.

## 1C.1

### **Using Spin-Hall MTJs to Build an Energy-Efficient In-memory Computation Platform**

*Masoud Zabihi<sup>1</sup>, Zhengyang Zhao<sup>1</sup>, Mahendra DC<sup>2</sup>, Zamshed I. Chowdhury<sup>1</sup>*

*Salonik Resch<sup>1</sup>, Thomas Peterson<sup>2</sup>, Ulya R. Karpuzcu<sup>1</sup>, Jian-Ping Wang<sup>1</sup>*

*Sachin S. Sapatnekar<sup>1</sup>*

**<sup>1</sup>Department of Electrical and Computer Engineering, University of Minnesota**

**<sup>2</sup>School of Physics and Astronomy, University of Minnesota**

\* Authors of best papers are honored during the Synopsys sponsored luncheon on Wednesday March 6

# ISQED 2019 Organizing Committee

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**Ali A. Iranmanesh**

Silicon Valley Polytechnic Inst.

## GLOBAL REPRESENTATIVES

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**George P. Alexiou**

University of Patras and  
RA-CTI, Patras, Greece

**China Chair**

**Gaofeng Wang**

Hangzhou Dianzi University

**Brazil & South America Chair**

**Fabiano Passuelo Hessel**

Pontificia Universidade Catolica do Rio  
do Sul, Brazil

**Japan Chair**

**Masahiro Fujita**

University of Tokyo

**Taiwan Chair**

**Shih-Hsu Huang**

Chung Yuan Christian  
University

## TECHNICAL PROGRAM COMMITTEES

**Swaroop Ghosh**- Pennsylvania State University (Chair)

**Kurt Schwartz**- Texas Instruments (Co-Chair)

### IoT –Design & Smart Sensors (SSDT)

**Xiaoning Qi**, C-SKY Microsystems Corp (Chair)

**Libor Ruffer**, University of Grenoble-Alpes (Co-Chair)

#### Committee Members:

**Pradeep Chawda** - Texas Instruments

**Abishai Daniel** - Intel

**Vittorio Ferrari** - University of Brescia

**Zhong Guan** - UC Santa Barbara

**Jaydeep Kulkarni** - University of Texas at Austin

**Joshua Lee** - City University of Hong Kong

**Michel Maharbiz** - U.C. Berkeley

**Maria Malik** - Intel

**Thilo Sauter** - Danube University Krems

**Kazuyuki Tomida** - SONY

**Yanzhi Wang** - University of Southern California

# TECHNICAL PROGRAM COMMITTEES

(continued)

## Cognitive Computing in Hardware (CCH)

Yang (Cindy) Yi, Virginia Tech (Chair)  
Deliang Fan, University of Central Florida (Co-Chair)

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Abishai Daniel - Intel  
Xin Fu - University of Houston  
Miao Hu - Binghamton University  
Hao Jiang - San Francisco State University  
Omid Kavehei - The University of Sydney  
Amey Kulkarni - Velodyne LiDAR  
Xue Lin - Northeastern University

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## Hardware and System Security (HSS)

Gang Qu, Univ. of Maryland, College Park (Chair)  
Anupam Chattopadhyay, Nanyang Technological University (Co-Chair)

### Committee Members:

Shivam Bhasin - Temasek Laboratories, Nanyang Technological University  
Jia Di - University of Arkansas  
Swaroop Ghosh - Pennsylvania State University  
Anirudh Iyengar - Intel Corp.  
Yier Jin - University of Florida  
Sachhith Kannan - Intel Corp.  
Amey Kulkarni - Velodyne LiDAR  
Seetharam Narasimhan - Intel Corp  
Francesco Regazzoni - ALaRI  
fareena saqib - University of North Carolina at Charlotte  
Ioannis Savidis - Drexel University  
Xiaowei Xu - Huazhong university of science and technology  
Weize Yu - Old Dominion University  
Jiliang Zhang - Hunan University

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## Design Technology Co-Optimization (DTCO)

Rajan Beera, Pall Corporation (Chair)  
Sumeet Gupta, Purdue University (Co-Chair)

### Committee Members:

Tuhin Guha Neogi  
Chenyun Pan - University of Kansas  
Kun Qian - GLOBALFOUNDRIES  
Mustafa Berke Yelten - Istanbul Technical University

# TECHNICAL PROGRAM COMMITTEES

(continued)

## Design Verification and Design Testability (DVFT)

Sreejit Chakravarty, Intel Corporation (Chair)

Vinod Viswanath, Real Intent, Inc. (Co-Chair)

### Committee Members:

George Alexiou - Univ. Of PATRAS

Alberto Bosio - Lyon Institute of Nanotechnology

Soumya Chakraborty - Cypress Semiconductors

Serge Demidenko - Sunway University

Michael Hsiao - Virginia Tech

Chrysovalantis Kavousianos - University of Ioannina

Jon Nafziger - Texas Instruments

Dimitris Nikolos - University of Patras

Ernesto Sanchez - Politecnico di Torino

Arani Sinha - Intel

Spyros Tragoudas - Southern Illinois University Carbondale

Yiorgos Tsiatouhas - University of Ioannina

Miroslav N. Velez - Aries Design Automation

Arnaud Virazel - LIRMM

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## EDA, Physical Design, and IP Cores (EDA)

Srinivas Katkooori, University of South Florida (Chair)

Srini Krishnamoorthy, Apple Inc. (Co-Chair)

### Committee Members:

Yici Cai - Tsinghua Univ.

Eric Foreman - IBM

Dhruva Ghai - ORIENTAL UNIVERSITY INDORE

Shih-Hsu Huang - Chung Yuan Christian University

Anand Iyer - Microsoft

Yu-Min Lee - National Chiao Tung University

Rung-Bin Lin - Yuan Ze University

Ofelya Manukyan - CAD/EDA R&D, Synopsys

Gayatri Mehta - University of North Texas

Rajeev Murgai - Synopsys India Pvt. Ltd.

Siddhartha Nath - Synopsys Inc.

Andre Reis - UFRGS

Emre Salman - Stony Brook University

Takashi Sato - Kyoto University

Vinod Viswanath - Real Intent, Inc.

Jia Wang - Illinois Institute of Technology

Hua Xiang - IBM Research

# TECHNICAL PROGRAM COMMITTEES

(continued)

## Emerging Process&Device Tech. &Design Issues (EDT)

Shih-Hung Chen, Imec (Chair)  
Jayita Das, Intel Corp. (Co-Chair)

### Committee Members:

Abishai Daniel - Intel  
Vita Pi-Ho Hu - National Central University  
Nikos Konofaos - Aristotle University of Thessaloniki  
Chun-Yu Lin - National Taiwan Normal University  
Renato Ribas - UFRGS  
Swatilekha Saha - Cypress Semiconductor Corporation  
Rasit Onur Topaloglu - IBM

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## Integrated Circuit Design (ICD)

Aswin Mehta, Texas Instruments Inc (Chair)  
Jose Pineda, NXP Semiconductors (Co-Chair)

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Karan Bhatia - Texas Instruments, Inc.  
Paulo Butzen - Universidade Federal do Rio Grande - FURG  
subho chatterjee - intel corporation  
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Riaz Naseer - Rockwell Automation  
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Kurt Schwartz - Texas Instruments  
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Vishnoi Upasna - Marvell Semiconductor Inc.  
Amir Zjajo - Delft University of Technology

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# TECHNICAL PROGRAM COMMITTEES

(continued)

## System-level Design and Methodologies (SDM)

Rajesh Berigei, MathWorks (Chair)  
Shiyan Hu, Michigan Technological University (Co-Chair)

### Committee Members:

Kai Cong - Intel Corporation  
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Georgios Keramidas - Think Silicon S.A.  
Selcuk Kose - University of South Florida  
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Sudeep Pasricha - Colorado State University  
Paul (C.P.) Paul - National Chiao Tsung University  
Shanq-Jang Ruan - National Taiwan University of Sci. and Tech.  
Tuna Tarim - Texas Instrument  
Jeremy Tolbert - IBM  
Pravin Kumar Venkatesan - Velodyne Lidar  
Bei Yu - The Chinese University of Hong Kong

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## 3 Dimensional Integration & Adv. Packaging (TDIP)

Payman Zarkesh-Ha, University of New Mexico (Chair)  
Shreepad Panth, Altera Corporation, An Intel Company (Co-Chair)  
Dae Hyun Kim, Washington State University (Co-Chair)

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Saurabh Sinha - ARM Inc.  
Jianyong Xie - Intel  
Ehrenfried Zschech - Fraunhofer IKTS

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## Special Sessions

Vinod Viswanath, Real Intent, Inc. (Chair)  
Abhilash Goyal, IEEE Member (Co-Chair)  
Amey Kulkarni, Velodyne LiDAR (Co-Chair)

# NOTES

# GENERAL INFORMATION

## ISQED 2019 GENERAL INFORMATION

March 6-7, 2019  
Santa Clara Convention Center  
5001 Great America Pkwy, Santa Clara, CA 95054

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### KEYNOTE SPEECHES

Wednesday, March 6, 8:45 AM - 9:45 AM  
Meeting Rooms 203/204

#### Adversarial attacks on Security and Privacy of Machine Learning Systems

**Sandip Kundu**  
Program Director  
National Science Foundation (NSF)  
.....

Thursday, March 7, 9:00 AM - 9:45 AM  
Meeting Rooms 203/204

#### Machine Learning is Changing the Game for Variability and Characterization and will soon help Analog and Digital Verification

**Amit Gupta**  
General Manager of the IC Verification Solutions  
Solido division  
Mentor, a Siemens Business  
.....

## Luncheon Panel Discussion

Wednesday, March 6, 12:00 PM - 1:25 PM  
Meeting Rooms 203/204

### Hype or hope: Is Machine Learning the Next Generation of Design and Design Automation?

Machine Learning (ML) has become popular in recent technology. Knowingly or not knowingly we benefit from different ML applications: Google Maps takes us to our destination in the most efficient way and tells us about an accident that may have happened, Amazon Alexa answers our questions and plays our favorite songs, our favorite online shopping site recommends items for us to purchase. We may not love it but we can not leave it either as ML is here to stay. This panel will discuss the impact of ML on design and design automation. How is the semiconductor industry adopting ML, what design automation applications are we working on, what is the outcome? Is ML hype or hope? Join us to listen to our panelists' thoughts on ML and its place in design and design automation.

#### Chair & Moderator:

**Tuna Tarim** - Texas Instruments (Chair)  
**Li-C Wang** - University of California - Santa Barbara (Co-Chair)  
**Peng Li** - Texas A&M University (Co-Chair)

#### Panelists:

**Elyse Rosenbaum** - Melvin and Anne Louise Hassebrock Professor in Electrical and Computer Engineering, University of Illinois at Urbana-Champaign  
**Mark Ren** - Principal Research Scientist, NVIDIA  
**Noel Menezes** - Director Strategic CAD Labs, Intel  
**Pradiptya Ghosh** - Sr. Director of Engineering, Mentor Graphics  
**Sachin Sapatnekar** - Distinguished McKnight University Professor and the Henle Chair Professor in Electrical and Computer Engineering at the University of Minnesota

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# GENERAL INFORMATION

## ISQED LUNCH & AWARDS CEREMONY

*Wednesday, March 6, 11:20 AM - 12:00 PM*  
**Meeting Rooms 203/204**

### ISQED Best Paper Awards

Recipients of the ISQED 2019 Best Paper Award will be recognized during the ISQED luncheon on Wednesday. The best paper is shown in Page 2 of this document.

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## Embedded Tutorials

### Chair & Moderators:

**Shiyan Hu** - Michigan Technological University (Chair)  
**José Pineda de Gyvez** - Eindhoven University of technology (Co-Chair)  
**Jie Gu** - Northwestern University (Co-Chair)

**Meeting Rooms 203/204**

*Wednesday, March 6, 1:35 PM - 2:35 PM*

### **Tools and approaches to efficiently implement Deep Learning in embedded systems**

**Dr. Marc Duranton**  
CEA (French Atomic Energy Commission)

.....  
*Wednesday, March 6, 2:35 PM - 3:35 PM*

### **Spiking Neural Networks for Artificial Vision. From Sensing, to Processing and Learning**

**Dr. B. Linares-Barranco**  
Scientist, Instituto de Microelectronica de Sevilla

.....

## Embedded Tutorials

**Meeting Rooms 203/204**

*Thursday, March 7, 1:30 PM - 2:30 PM*

### **Developments and Practices for Testing MRAM Memories**

**Dr. Patrick Girard**  
LIRMM - CNRS / France

.....

*Thursday, March 7, 2:30 PM - 3:30 PM*

### **High Energy Efficient Reconfigurable Neural Network Processor Design**

**Dr. Shouyi Yin**  
Professor/Vice Director, Institute of Microelectronics  
Tsinghua University

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## TECHNICAL SESSIONS

There are a total of 13 paper sessions held on Wednesday and Thursday. Technical sessions are held in the format of two-three parallel tracks in **Meeting Rooms 201, 206 & 207**.

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## ON-SITE REGISTRATION

Schedule of on-site registration is as follows:

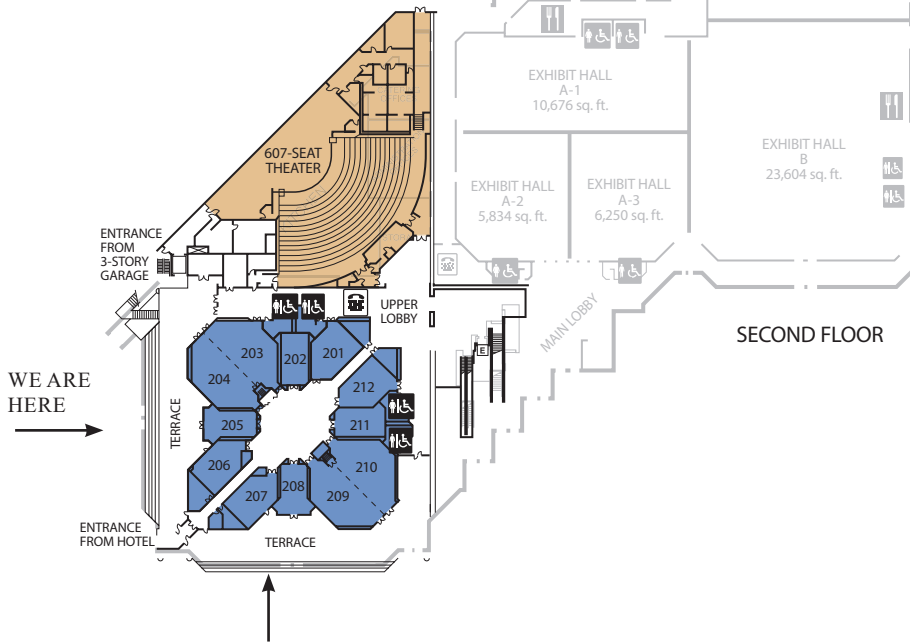
<i>Wednesday, March 6</i>	<i>8:00 AM - 3:00 PM</i>
<i>Thursday, March 7</i>	<i>8:00 AM - 1:00 PM</i>

Registration desk location will be beside the Meeting rooms 203/204.

# FLOOR PLAN



**SANTA CLARA**  
CONVENTION CENTER  
2nd Floor



**Santa Clara Convention Center**  
**2nd Floor**

General Sessions & Tutorials:  
Meeting Rooms 203/204

Breakout Rooms:  
Meeting Rooms, 201, 206 and 207

# PROGRAM AT A GLANCE

ISQED 2019 PROGRAM AT A GLANCE					
DATE	TIME				
WEDNESDAY 3/6/2019	8:45AM -9:45AM	<p><b>KEYNOTE SPEECH</b> (MEETING ROOMS 203/204)</p> <p><b>ADVERSARIAL ATTACKS ON SECURITY AND PRIVACY OF MACHINE LEARNING SYSTEMS</b> SANDIP KUNDU - NATIONAL SCIENCE FOUNDATION(NSF)</p>			
	9:45 AM - 10:00 AM	MORNING BREAK			
	10:00 AM -11:20 AM	<table border="1"> <tr> <td> <p><b>SESSION 1A</b> MACHINE LEARNING IN CONVENTIONAL AND EMERGING PLATFORMS</p> <p>MEETING ROOM 201</p> </td> <td> <p><b>SESSION 1B</b> MODERN HIGH-LEVEL AND LOGIC SYNTHESIS</p> <p>MEETING ROOM 206</p> </td> <td> <p><b>SESSION 1C</b> EMERGING MEMORY AND SPINTRONICS TECHNOLOGIES FOR FUTURE ENERGY EFFICIENT APPLICATIONS</p> <p>MEETING ROOM 207</p> </td> </tr> </table>	<p><b>SESSION 1A</b> MACHINE LEARNING IN CONVENTIONAL AND EMERGING PLATFORMS</p> <p>MEETING ROOM 201</p>	<p><b>SESSION 1B</b> MODERN HIGH-LEVEL AND LOGIC SYNTHESIS</p> <p>MEETING ROOM 206</p>	<p><b>SESSION 1C</b> EMERGING MEMORY AND SPINTRONICS TECHNOLOGIES FOR FUTURE ENERGY EFFICIENT APPLICATIONS</p> <p>MEETING ROOM 207</p>
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	11:20 AM -12:00 PM	<p><b>ISQED LUNCHEON &amp; PANEL</b> MEETING ROOMS 203/204 BEST PAPER AWARDS , COMMITTEE RECOGNITION</p> <p><b>synopsys</b> Silicon to Software</p>			
	12:00 PM -1:25 PM	<p><b>PANEL DISCUSSION</b></p> <p><b>HYPE OR HOPE: IS MACHINE LEARNING THE NEXT GENERATION OF DESIGN AND DESIGN AUTOMATION?</b></p>			
	1:25 PM -1:35 PM	BREAK			
	1:35 PM -2:35 PM	<p><b>EMBEDDED TUTORIAL 1</b></p> <p><b>TOOLS AND APPROACHES TO EFFICIENTLY IMPLEMENT DEEP LEARNING IN EMBEDDED SYSTEMS</b></p> <p>MEETING ROOMS 203/204</p>			
	2:35 PM -3:35 PM	<p><b>EMBEDDED TUTORIAL 2</b></p> <p><b>SPIKING NEURAL NETWORKS FOR ARTIFICIAL VISION. FROM SENSING, TO PROCESSING AND LEARNING</b></p> <p>MEETING ROOMS 203/204</p>			
	3:35 PM -3:45 PM	AFTERNOON BREAK			
	3:45 PM -5:25 PM	<table border="1"> <tr> <td> <p><b>SESSION 2A</b> ADVANCES IN SIMULATION, DESIGN OPTIMIZATION AND DEBUG</p> <p>MEETING ROOM 201</p> </td> <td> <p><b>SESSION 2B</b> SYSTEM LEVEL TOOLS, FLOWS, METHODS</p> <p>MEETING ROOM 206</p> </td> <td> <p><b>SESSION 2C</b> HIGH PERFORMANCE APPLICATION SPECIFIC ARCHITECTURE</p> <p>MEETING ROOM 207</p> </td> </tr> </table>	<p><b>SESSION 2A</b> ADVANCES IN SIMULATION, DESIGN OPTIMIZATION AND DEBUG</p> <p>MEETING ROOM 201</p>	<p><b>SESSION 2B</b> SYSTEM LEVEL TOOLS, FLOWS, METHODS</p> <p>MEETING ROOM 206</p>	<p><b>SESSION 2C</b> HIGH PERFORMANCE APPLICATION SPECIFIC ARCHITECTURE</p> <p>MEETING ROOM 207</p>
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	5:25 PM -6:45 PM	POSTER PAPERS AND MIXER			
	THURSDAY 3/7/2019	9:00 AM -9:45 AM	<p><b>KEYNOTE SPEECH</b> (MEETING ROOMS 203/204)</p> <p><b>MACHINE LEARNING IS CHANGING THE GAME FOR VARIABILITY AND CHARACTERIZATION AND WILL SOON HELP ANALOG AND DIGITAL VERIFICATION</b> AMIT GUPTA - GENERAL MANAGER OF THE IC VERIFICATION SOLUTIONS SOLIDO DIVISION OF MENTOR, A SIEMENS BUSINESS</p> <p><b>Mentor</b> A Siemens Business</p>		
9:45 AM -10:00 AM		MORNING BREAK			
10:00 AM -11:20 AM		<table border="1"> <tr> <td> <p><b>SESSION 3A</b> DEEP LEARNING CIRCUITS AND ARCHITECTURES</p> <p>MEETING ROOM 201</p> </td> <td> <p><b>SESSION 3B</b> INNOVATIONS IN CLASSIC HARDWARE SECURITY PROBLEMS</p> <p>MEETING ROOM 206</p> </td> <td> <p><b>SESSION 3C</b> CO-OPTIMIZATIONS OF DEVICE PERFORMANCE AND DESIGN RELIABILITY FROM STATE-OF-THE-ART FINFET TO QUANTUM TECHNOLOGIES</p> <p>MEETING ROOM 207</p> </td> </tr> </table>	<p><b>SESSION 3A</b> DEEP LEARNING CIRCUITS AND ARCHITECTURES</p> <p>MEETING ROOM 201</p>	<p><b>SESSION 3B</b> INNOVATIONS IN CLASSIC HARDWARE SECURITY PROBLEMS</p> <p>MEETING ROOM 206</p>	<p><b>SESSION 3C</b> CO-OPTIMIZATIONS OF DEVICE PERFORMANCE AND DESIGN RELIABILITY FROM STATE-OF-THE-ART FINFET TO QUANTUM TECHNOLOGIES</p> <p>MEETING ROOM 207</p>
<p><b>SESSION 3A</b> DEEP LEARNING CIRCUITS AND ARCHITECTURES</p> <p>MEETING ROOM 201</p>		<p><b>SESSION 3B</b> INNOVATIONS IN CLASSIC HARDWARE SECURITY PROBLEMS</p> <p>MEETING ROOM 206</p>	<p><b>SESSION 3C</b> CO-OPTIMIZATIONS OF DEVICE PERFORMANCE AND DESIGN RELIABILITY FROM STATE-OF-THE-ART FINFET TO QUANTUM TECHNOLOGIES</p> <p>MEETING ROOM 207</p>		
11:20 AM -11:40 AM		MORNING BREAK			
11:40 AM -1:00 PM		<table border="1"> <tr> <td> <p><b>SESSION 4A</b> ARTIFICIAL INTELLIGENCE FOR EFFICIENT APPLICATION SPECIFIC HARDWARE</p> <p>MEETING ROOM 201</p> </td> <td> <p><b>SESSION 4B</b> VERIFICATION, ATPG AND FAILURE ANALYSIS</p> <p>MEETING ROOM 206</p> </td> </tr> </table>	<p><b>SESSION 4A</b> ARTIFICIAL INTELLIGENCE FOR EFFICIENT APPLICATION SPECIFIC HARDWARE</p> <p>MEETING ROOM 201</p>	<p><b>SESSION 4B</b> VERIFICATION, ATPG AND FAILURE ANALYSIS</p> <p>MEETING ROOM 206</p>	
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1:00 PM -1:30 PM		LUNCH BREAK			
1:30 PM -2:30 PM		<p><b>EMBEDDED TUTORIAL 3</b></p> <p><b>DEVELOPMENTS AND PRACTICES FOR TESTING MRAM MEMORIES</b></p> <p>MEETING ROOMS 203/204</p>			
2:30 PM -3:30 PM		<p><b>EMBEDDED TUTORIAL 4</b></p> <p><b>HIGH ENERGY EFFICIENT RECONFIGURABLE NEURAL NETWORK PROCESSOR DESIGN</b></p> <p>MEETING ROOMS 203/204</p>			
3:30 PM -3:40 PM		AFTERNOON BREAK			
3:40 PM -5:00 PM		<table border="1"> <tr> <td> <p><b>SESSION 5A</b> PHYSICAL DESIGN OPTIMIZATION</p> <p>MEETING ROOM 201</p> </td> <td> <p><b>SESSION 5B.1</b> 3D INTEGRATION &amp; ADVANCED PACKAGING</p> <p><b>SESSION 5B.2</b> FUTURE OF SOC ARCHITECTURES AND VERIFICATION</p> <p>MEETING ROOM 206</p> </td> </tr> </table>	<p><b>SESSION 5A</b> PHYSICAL DESIGN OPTIMIZATION</p> <p>MEETING ROOM 201</p>	<p><b>SESSION 5B.1</b> 3D INTEGRATION &amp; ADVANCED PACKAGING</p> <p><b>SESSION 5B.2</b> FUTURE OF SOC ARCHITECTURES AND VERIFICATION</p> <p>MEETING ROOM 206</p>	
<p><b>SESSION 5A</b> PHYSICAL DESIGN OPTIMIZATION</p> <p>MEETING ROOM 201</p>		<p><b>SESSION 5B.1</b> 3D INTEGRATION &amp; ADVANCED PACKAGING</p> <p><b>SESSION 5B.2</b> FUTURE OF SOC ARCHITECTURES AND VERIFICATION</p> <p>MEETING ROOM 206</p>			

Wednesday March 6

8:45 AM - 9:45 AM

Meeting Rooms 203/204

### Adversarial Attacks on Security and Privacy of Machine Learning



**Sandip Kundu**

*Program Director, National Science Foundation (NSF)*

As applications of machine learning (ML) have become commonplace in healthcare, security, finance and many other mission critical systems, the security risk of machine-learning systems is emerging as a concern. Machine learning applications evolve through multiple stages including data collection, preparation, labeling, model training, testing and deployment. Malicious actors can impact the reliability and dependability of machine learning system by exploiting vulnerability at any of these stages. In this talk, we present a taxonomy for attack that categorizes an attack based on three fundamental pillars of information security, namely, confidentiality, integrity, and availability. In confidentiality violation, an adversary uses the ML responses to infer the model parameters, or the secret information used in learning process. In an integrity violation, the attacker causes to allow harmful instances to slip through the ML model as false negatives. In an availability violation, the attacker creates a denial of service event. We conclude the talk with various approaches for defending against adversarial attack on ML system.

#### **About Sandip Kundu**

Sandip Kundu is a Program Director at the National Science Foundation in the CNS division within the CISE directorate. He is serving in this position on leave from the University of Massachusetts at Amherst, where he is a professor in Electrical and Computer Engineering Department. Kundu began his career at IBM Research as a Research Staff Member; then worked at Intel Corporation as a Principal Engineer before joining UMass Amherst as a professor in 2005. He has published over 250 research papers in VLSI design and test, holds several key patents including ultra-drowsy sleep mode in processors, and has given more than a dozen tutorials at various conferences. He is a Fellow of the IEEE, Fellow of the Japan Society for Promotion of Science (JSPS), Senior International Scientist of the Chinese Academy of Sciences and was a Distinguished Visitor of the IEEE Computer Society. He is currently an Associate Editor of the IEEE Transactions on Dependable and Secure Computing. Previously, he has served as an Associate Editor of the IEEE Transactions on Computers, IEEE Transactions on VLSI Systems and ACM Transactions on Design Automation of Electronic Systems. He has been Technical Program Chair/General Chair of multiple conferences including ICCD, ATS, ISVLSI, DFTS and VLSI Design Conference.





## Panel Discussion

Wednesday March 6

12:00 PM – 1:25 PM

Meeting Rooms 203/204

### Hype or Hope: Is Machine Learning the Next Generation of Design and Design Automation?

**Summary:** Machine Learning (ML) has become popular in recent technology. Knowingly or not knowingly we benefit from different ML applications: Google Maps takes us to our destination in the most efficient way and tells us about an accident that may have happened, Amazon Alexa answers our questions and plays our favorite songs, our favorite online shopping site recommends items for us to purchase. We may not love it but we can not leave it either as ML is here to stay. This panel will discuss the impact of ML on design and design automation. How is the semiconductor industry adopting ML, what design automation applications are we working on, what is the outcome? Is ML hype or hope? Join us to listen to our panelists' thoughts on ML and its place in design and design automation.

#### **Moderator and Chairs:**

**Tuna Tarim** - *Texas Instruments (Chair)*

**Li-C Wang** - *University of California – Santa Barbara (Co-Chair)*

**Peng Li** - *Texas A&M University (Co-Chair)*

#### **Panelists:**

**Elyse Rosenbaum** - *Melvin and Anne Louise Hassebrock Professor in Electrical and Computer Engineering, University of Illinois at Urbana-Champaign*

**Mark Ren** - *Principal Research Scientist, NVIDIA*

**Noel Menezes** - *Director Strategic CAD Labs, Intel*

**Pradiptya Ghosh** - *Sr. Director of Engineering, Mentor Graphics*

**Sachin Sapatnekar** - *Distinguished McKnight University Professor and the Henle Chair Professor in Electrical and Computer Engineering at the University of Minnesota*

**Manish Pandey** - *Synopsys Fellow, and an Adjunct Professor at Carnegie Mellon University*

## ISQED Keynote 2P.1

Thursday March 7

9:00 AM - 9:45 AM

Meeting Rooms 203/204

### **Machine Learning is Changing the Game for Variability and Characterization and will soon help Analog and Digital Verification**



**Amit Gupta**

*General Manager of the IC Verification Solutions Solido division  
Mentor Graphics, a Siemens Business*

The Golden Age of machine learning is upon EDA. Over the past four years, we have seen large EDA suppliers and customers grow their internal ML teams and strategies, and ML research projects are emerging in all areas of EDA. But, we have not yet seen much of this investment convert into real production flows and work. This talk reviews a set of challenges that make it difficult to bring ML solutions to production for semiconductor design, and discusses approaches for solving them. We will discuss how these approaches are already benefiting variation-aware design and characterization flows, and the broader applicability to analog and digital verification.

#### **About Amit Gupta**

Amit Gupta is General Manager of the IC Verification Solutions Solido division of Mentor, a Siemens Business. Previously, he founded Solido Design Automation Inc. in 2005 and served as its President and CEO until its acquisition by Mentor in 2017. Solido is a leader in machine learning variation-aware design and characterization software. In 1999, he founded Analog Design Automation Inc. (ADA), and served as its President, CEO and VP of Business Development until it was acquired by Synopsys in 2004. ADA was a leader in analog optimization software. He has previously served as a Director of the Electronic Design Automation Consortium. Amit holds degrees in both Electrical Engineering and Computer Science with great Distinction from the University of Saskatchewan, and was awarded the 2005 outstanding alumni award for significant accomplishments since graduation.

# Embedded Tutorial 1

Wednesday March 6

1:35 PM - 2:35 PM

Meeting Rooms 203/204

## Tools and approaches to efficiently implement Deep Learning in embedded systems



**Dr. Marc Duranton**

***CEA (French Atomic Energy Commission)***

Summary: Artificial Intelligence, and more particularly Deep Learning are enablers of new applications, and allow computing systems to better interact with the real world by extracting information from signals, images and sounds. But they are demanding in computing power and therefore energy, and pose challenges for being used in embedded systems. This presentation will present some uses cases, tools, approaches and hardware allowing to select neural networks and hardware implementations tuned for embedded applications (Deep Learning at the edge). It will also include some highlight on Auto-ML and on computations using “spiking” data representation.”

### **About Marc Duranton**

Dr. Marc Duranton is a member of the Architecture, IC Design & Embedded Software Division of the Research and Technology Department of CEA (French Atomic Energy Commission), where he is involved in realizations for Deep Learning and on Cyber Physical Systems. He previously spent more than 23 years in Philips and Philips Semiconductors where he led the development of the family of L-Neuro chips, digital processors using artificial neural networks techniques. He also worked on several video coprocessors for the VLIW processor TriMedia and for various Nexasia platforms. In NXP Semiconductors, he was in charge of Ne-XVP project that targeted the design of the hardware and software of a multi-core processor for real-time applications and for consumer video processing.

His interests include Deep Learning, Artificial Intelligence and emerging paradigms for computing systems, HPC, embedded systems, (Cognitive) Cyber Physical Systems, parallel architectures for high performance and real-time processing, models of computation and communication with time guaranties. He is a member of the College of Ethics of CEA on “Moral issues in automatic decision-making processes”.

## Embedded Tutorial 2

Wednesday March 6

2:35 PM -3:35 PM

Meeting Rooms 203/204

### **Spiking Neural Networks for Artificial Vision. From Sensing, to Processing and Learning**



**Dr. B. Linares-Barranco**

***Scientist, Instituto de Microelectronica de Sevilla***

Summary: The brain processes information in a very efficient manner by using some kind of spike encoding technique, despite the fact that the underlying technology (neurons) is slow, faulty, and noisy. Since decades neuromorphic engineering has attempted to imitate the sensing and processing of biological neural systems with the hope to develop artificial systems capable of approaching the brain capabilities. We will present CMOS spiking vision sensors and spiking based processing techniques that allow for extremely fast recognition capabilities. Additionally, emerging memory technologies (such as RRAM) have the potential to be exploited for implementing self-learning and/or highly compact spike processing systems. We will review show some techniques for implementing such capabilities.

#### **About B. Linares-Barranco**

B. Linares-Barranco received a PhD degree in 1990 from Univ. of Sevilla, Spain on Analog CMOS Oscillators, and a second PhD degree from Texas A&M Univ. in 1991 on CMOS Analog Neural Networks Implementations. In 1991 he became Tenured Scientist of the Spanish Research Council (CSIC) at the "Instituto de Microelectronica de Sevilla" (Sevilla Microelectronics Institute). In 2004 he was promoted to CSIC Full Professor, and since February 2018 he is the Director of the Institute. His research has focused on Neuromorphic Engineering, developing event-driven (spiking) vision sensors, convolution processors, and unsupervised spike-based learning systems. He is co-founder of Prophesee and GrAI-Matter-Labs, two companies whose objectives include commercializing spiking vision sensor applications. During the past two decades he has been involved in several European projects for developing spiking systems, neuromorphic computing systems, and application of emerging memory nanotechnologies to neuromorphic systems. He has also been part of the Human Brain Project (European Commission Flagship).

## Embedded Tutorial 3

Thursday March 7

1:30 PM - 2:30 PM

Meeting Rooms 203/204

### Developments and Practices for Testing MRAM Memories



**Dr. Patrick Girard**  
***LIRMM - CNRS / France***

Summary: Memories occupy most of the silicon area in nowadays System-on-Chips. Though widely used, non-volatile Flash memories still have several drawbacks. MRAMs have the potential to mitigate almost all Flash related issues. However, they are prone to defects as any other kind of memories. This embedded tutorial provides an up-to-date and practical coverage of MRAM testing. The first part gives some background on Magnetic Tunnel Junction and existing MRAM technologies. Then, an MRAM architecture used to illustrate the development of test and reliability solutions is presented. The next part detailed resistive-open, resistive-bridge and capacitive defect injection campaigns that are usually performed in order to analyze specific failure mechanisms of MRAMs. Specific functional fault models associated to these failure mechanisms are then described. The last part of the tutorial presents March test algorithms developed for MRAM testing and their validation in industrial environments.

#### **About Patrick Girard**

Patrick GIRARD received a M.Sc. degree in Electrical Engineering and a Ph.D. degree in Microelectronics from the University of Montpellier, France, in 1988 and 1992 respectively. He is currently Research Director at CNRS (French National Center for Scientific Research) and works in the Microelectronics Department of the Laboratory of Informatics, Robotics and Microelectronics of Montpellier (LIRMM) - France. From 2010 to 2014, he was head of this Microelectronics Department. He is co-Director of the International Associated Laboratory « LAFISI » (French-Italian Research Laboratory on Hardware-Software Integrated Systems) created in 2013 by the CNRS and the University of Montpellier with the Politecnico di Torino, Italy. His research interests include all aspects of digital testing and memory testing, with emphasis on critical constraints such as timing and power. Reliability and fault tolerance are also part of his research activities. He has served on numerous conference committees and is the founder and Editor-in-Chief of the ASP Journal of Low Power Electronics (JOLPE). He is also an Associate Editor of the IEEE Transactions on Computers, IEEE Transactions on CAD and the Journal of Electronic Testing – Theory and Applications (JETTA - Springer). He has supervised 37 PhD dissertations and has published 7 books or book chapters, 65 journal papers, and more than 230 conference and symposium papers on these fields. Patrick Girard is a Fellow of IEEE.

# Embedded Tutorial 4

Thursday March 7

2:30 PM - 3:30 PM

Meeting Rooms 203/204

## High Energy Efficient Reconfigurable Neural Network Processor Design



**Dr. Shouyi Yin**

***Professor/Vice Director , Institute of Microelectronics Tsinghua University***

Summary: With the rapid development of information technology, the emerging applications, especially artificial intelligence (AI), bring severe challenges to both energy efficiency (the ratio of performance to energy consumption) and flexibility of computing chips. The traditional computing chips with software programming (such as CPU) or hardware programming (such as FPGA) are difficult to meet the requirements of high energy efficiency. Application Specific Integrated Circuit (ASIC) has high energy efficiency, but the poor flexibility restricts its application under the pressure of high cost of <10nm process technology. Coarse-grained reconfigurable computing is a promising solution which combines high energy-efficiency of hardwired logics and high flexibility of software programming. In the reconfigurable architecture, computing units, storage units and interconnection resources compose a regular parallel and distributed processing element (PE) array, which is dynamic reconfigurable. The software applications (programmed by high-level language, such as C) are synthesized into configuration context for reconfiguring hardware resources at run time. In this tutorial, a survey of basic ideas and recent techniques of coarse-grained reconfigurable architecture (CGRA) is presented. A preliminary analysis of the current challenges and future trends of AI processors are introduced to understand the system constraints, and translate them into design specifications. Then several practical reconfigurable processors are presented to demonstrate the potential and benefits of CGRA. As particularly important case, low-power neural networks processors are discussed by highlighting the “reconfigurability” that are enabling the recent and very rapid improvements in energy efficiency.

### **About Shouyi Yin**

Dr. Shouyi Yin received the B.S., M.S., and Ph.D. degrees in electronic engineering from Tsinghua University, Beijing, China, in 2000, 2002, and 2005, respectively. He has worked with Imperial College, London, U.K., as a Research Associate. He is currently associate professor (Tenured) and vice director of Institute of Microelectronics in Tsinghua University. His research interests include reconfigurable computing, domain-specific reconfigurable architecture design and high level synthesis. He has published more than 100 journal papers and more than 50 conference papers. He has received ACM/IEEE ISLPED Design Contest Award (2017), Second Prize of China’s State Technological Innovation Award (2015), China’s Patent Golden Award (2015), First Prize of Technological Innovation Award of Ministry of Education, China (2014), and Best Paper Award in China Communications IC Technology and Application Conference (2011). Dr. Shouyi Yin is the Secretary-General of EDA Chapter in Chinese Institute of Electronics. He is also the technical committee member of Asia Pacific Signal and Information Processing Association. Dr. Shouyi Yin has been served as program committee member and organizer in the tops VLSI and EDA conferences such as A-SSCC, DAC, ICCAD and ASPDAC. He is the associate editor of Integration, the VLSI journal and editorial board member of Journal of Low Power Electronics.

## SESSION 1A

Wednesday March 6

### Machine Learning in Conventional and Emerging Platforms

Chair: **Prof. Ronald DeMara**, University of Central Florida

Co-Chair: **Dr. Sicheng Li**, HPE

10:00AM

#### 1A.1

##### **kNN-CAM: A k-Nearest Neighbors-based Configurable Approximate Floating Point Multiplier**

*Ming Yan<sup>1</sup>, Yuntao Song<sup>2</sup>, Yiyu Feng<sup>2</sup>, Ghasem Pasandi<sup>3</sup>, Massoud Pedram<sup>2</sup>, Shahin Nazarian<sup>2</sup>*

<sup>1</sup>University of Southern California, Ming Hsieh Department of Electrical Engineering, <sup>2</sup>USC, <sup>3</sup>University of Southern California

10:20AM

#### 1A.2

##### **Processing-In-Memory Acceleration of Convolutional Neural Networks for Energy-Efficiency, and Power-Intermittency Resilience**

*Arman Roohi<sup>1</sup>, Shaahin Angizi<sup>2</sup>, Deliang Fan<sup>3</sup>, Ronald F DeMara<sup>3</sup>*

<sup>1</sup>Computer Systems and Architecture Laboratory, Department of EECS, University of Central Florida, <sup>2</sup>Department of Electrical and Computer Engineering, University of Central Florida, <sup>3</sup>University of Central Florida

10:40AM

#### 1A.3

##### **Towards Collaborative Intelligence Friendly Architectures for Deep Learning**

*Amir Erfan Eshratifar<sup>1</sup>, Amirhossein Esmaili<sup>1</sup>, Massoud Pedram<sup>2</sup>*

<sup>1</sup>University of Southern California, <sup>2</sup>USC

11:00AM

#### 1A.4

##### **A General Framework to Map Neural Networks onto Neuromorphic Processor**

*haowen fang<sup>1</sup>, Amar Shrestha<sup>1</sup>, Ziyi Zhao<sup>1</sup>, Yanzhi Wang<sup>2</sup>, Qinru Qiu<sup>1</sup>*

<sup>1</sup>syracuse university, <sup>2</sup>University of Southern California

## SESSION 1B

Wednesday March 6

### Modern High-Level and Logic Synthesis

Chair: **Srinivas Katkoori**, University of South Florida

Co-Chair: **Srini Krishnamoorthy**, Apple

10:00AM

#### 1B.1

#### **Approximate Logic Synthesis: A Reinforcement Learning-Based Technology Mapping Approach**

*Ghasem Pasandi<sup>1</sup>, Shahin Nazarian<sup>2</sup>, Massoud Pedram<sup>2</sup>*

<sup>1</sup>University of Southern California, <sup>2</sup>USC

10:20AM

#### 1B.2

#### **Fast Mapping-Based High-Level Synthesis of Pipelined Circuits**

*Chaofan Li<sup>1</sup>, Sachin S. Sapatnekar<sup>2</sup>, Jiang Hu<sup>3</sup>*

<sup>1</sup>Synopsys Inc., <sup>2</sup>University of Minnesota, <sup>3</sup>Texas A&M University

10:40AM

#### 1B.3

#### **Characterization of Fast, Accurate Leakage Power Models for IEEE P2416**

*Barkha Gupta and W. Rhett Davis*

North Carolina State University

11:00AM

#### 1B.4

#### **Synthesis of Algorithm Considering Communication Structure of Distributed/Parallel Computing**

*Yukio Miyasaka<sup>1</sup>, Ashish Mittal<sup>2</sup>, Masahiro Fujita<sup>1</sup>*

<sup>1</sup>University of Tokyo, <sup>2</sup>Indian Institute of Technology Bombay



## SESSION 1C

Wednesday March 6

### Emerging Memory and Spintronics Technologies for Future Energy Efficient Applications

Chair: **Aswin Mehta**, Texas Instruments

Co-Chair: **Prof. Vita Hu**, National Central University, Taiwan

10:00AM

#### 1C.1

##### **Using Spin-Hall MTJs to Build an Energy-Efficient In-memory Computation Platform**

*Masoud Zabihi, Zhengyang Zhao, Mahendra DC, Zamshed I. Chowdhury, Salonik Resch, Thomas Peterson, Ulya R. Karpuzcu, Jian-Ping Wang, Sachin S. Sapatnekar*  
University of Minnesota

10:20AM

#### 1C.2

##### **Low Restoration-Energy Differential Spin Hall Effect MRAM for High-Speed Nonvolatile SRAM Application**

*Sonal Shreya and Brajesh Kumar Kaushik*  
Indian Institute of Technology Roorkee

10:40AM

#### 1C.3

##### **A Multi-Driver Write Scheme for Reliable and Energy Efficient 1S1R ReRAM Crossbar Arrays**

*Sherif Amer<sup>1</sup> and Garrett Rose<sup>2</sup>*

<sup>1</sup>University of Tennessee, <sup>2</sup>The University of Tennessee

11:00AM

#### 1C.4

##### **Application of Probabilistic Spin Logic (PSL) in detecting satisfiability of a Boolean function**

*Vaibhav Agarwal<sup>1</sup> and Sneha Saurabh<sup>2</sup>*

<sup>1</sup>IITD, <sup>2</sup>Indraprastha Institute of Information Technology

## SESSION 2A

Wednesday March 6

### Advances in Simulation, Design Optimization and Debug

Chair: **Srini Krishnamoorthy**, Apple

Co-Chair: **Srinivas Katkoori**, University of South Florida

3:45PM

#### 2A.1

##### **A Compact Model of Negative Bias Temperature Instability Suitable for Gate-Level Circuit Simulation**

*Xu Liu<sup>1</sup>, Alessandro Bernardini<sup>2</sup>, Ulf Schlichtmann<sup>2</sup>, Xing Zhou<sup>1</sup>*

<sup>1</sup>Nanyang Technological University, <sup>2</sup>Technical University of Munich

4:05PM

#### 2A.2

##### **An Automated Design Flow for Synthesis of Optimal Switching Power Supply**

*Pradeep Chawda<sup>1</sup>, Anupriya Prasad<sup>1</sup>, Kunjal Rathod<sup>2</sup>, Kritika Solanki<sup>3</sup>*

<sup>1</sup>Texas Instruments, <sup>2</sup>VMWare, Inc, <sup>3</sup>Chhattisgarh Swami Vivekanand Technical University

4:25PM

#### 2A.3

##### **Robust Transistor Sizing for Improved Performances in Digital Circuits using Optimization Algorithms**

*Prateek Gupta<sup>1</sup>, Harshini Mandadapu<sup>2</sup>, Shirisha Gourishetty<sup>2</sup>, Zia Abbas<sup>2</sup>*

<sup>1</sup>IIT H, <sup>2</sup>International Institute of Information Technology, Hyderabad

4:45PM

#### 2A.4

##### **Resilient Reorder Buffer Design for Network-on-Chip**

*Zheng Xu<sup>1</sup> and Jacob Abraham<sup>2</sup>*

<sup>1</sup>ARM, Inc., <sup>2</sup>University of Texas

5:05PM

#### 2A.5

##### **Simulation Based Assessment of SRAM Data Retention Voltage**

*Zhipeng Dong, Xi Cao, Vivek Joshi, Muhammed Ahasan Ul Karim, Torsten Klick, Joerg Schmid*

GLOBALFOUNDRIES

## SESSION 2B

Wednesday March 6

### System Level Tools, Flows, Methods

Chair: **Dr. Brajesh Kumar Kaushik**, Indian Institute of Technology-Roorkee

Co-Chair: **Swaroop Ghosh**, Pennsylvania State University

3:45PM

#### 2B.1

#### **Evaluating Design Space Subsetting for Multi-Objective Optimization in Configurable Systems**

*Mohamad Hammam Alsafrijalani<sup>1</sup>, Tosiron Adegbiya<sup>2</sup>, Lokesh Ramamoorthi<sup>1</sup>*

<sup>1</sup>University of Miami, <sup>2</sup>University of Arizona

4:05PM

#### 2B.2

#### **A Scalable Image/Video Processing Platform with Open Source Design and Verification Environment**

*Xiaokun Yang<sup>1</sup>, Yunxiang Zhang<sup>1</sup>, Lei Wu<sup>2</sup>*

<sup>1</sup>University of Houston Clear Lake, <sup>2</sup>Auburn University at Montgomery

4:25PM

#### 2B.3

#### **Power-aware IoT based Smart Health Monitoring using Wireless Body Area Network**

*Jitumani Sarma<sup>1</sup>, Akash Katiyar<sup>2</sup>, Rakesh Biswas<sup>2</sup>, Hemanta Kumar Mondal<sup>2</sup>*

<sup>1</sup>Indian Institute of Information Technology, Guwahati, <sup>2</sup>Indian Institute of Information Technology Guwahati, India

4:45PM

#### 2B.4

#### **A Comprehensive Evaluation of Power Delivery Schemes for Modern Microprocessors**

*Jawad Haj-Yahya<sup>1</sup>, Efraim Rotem<sup>2</sup>, Avi Mendelson<sup>3</sup>, Anupam Chattopadhyay<sup>4</sup>*

<sup>1</sup>School of Computer Science and Engineering, Nanyang Technological University, <sup>2</sup>CPU Architect, Intel, Israel, <sup>3</sup>EE and CS Technion, Israel, <sup>4</sup>Nanyang Technological University

5:05PM

**2B.5**

**State Preserving Dynamic DRAM Bank Re-Configurations for Enhanced Power Efficiency**

*Kaustav Goswami<sup>1</sup>, Hemanta Kumar Mondal<sup>1</sup>, Shirshendu Das<sup>2</sup>, Dip Sankar Banerjee<sup>2</sup>*

<sup>1</sup>Indian Institute of Information Technology Guwahati India, <sup>2</sup>Indian Institute of Information Technology Guwahati

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## SESSION 2C

Wednesday March 6

### High Performance Application Specific Architecture

Chair: **Shomit Das**, AMD Research

Co-Chair: **Aswin Mehta**, Texas Instruments

3:45PM

#### 2C.1

##### **Deterministic Stochastic Computation Using Parallel Datapaths**

*Alexander Groszewski and Travis Lenz*

University of Texas at Austin

4:05PM

#### 2C.2

##### **MAPIM: Mat Parallelism for High Performance Processing in Non-volatile Memory Architecture**

*Joonseop Sim<sup>1</sup>, Minsu Kim<sup>2</sup>, Yeseong Kim<sup>3</sup>, Saransh Gupta<sup>4</sup>, Behnam Khaleghi<sup>4</sup>, Tajana Rosing<sup>5</sup>*

<sup>1</sup>University of California, San Diego, <sup>2</sup>University of Minnesota, <sup>3</sup>University of California San Diego, <sup>4</sup>University of California, San Diego, <sup>5</sup>UCSD

4:25PM

#### 2C.3

##### **Amoeba-Inspired Stochastic Hardware SAT Solver**

*Kazuaki Hara<sup>1</sup>, Naoki Takeuchi<sup>2</sup>, Masashi Aono<sup>3</sup>, Yuko Hara-Azumi<sup>1</sup>*

<sup>1</sup>Tokyo Institute of Technology, <sup>2</sup>Yokohama National University, <sup>3</sup>Keio University

4:45PM

#### 2C.4

##### **Accelerating Deterministic Bit-Stream Computing with Resolution Splitting**

*M. Hassan Najafi<sup>1</sup>, Sayed Abdolrasoul Faraji<sup>2</sup>, Bingzhe Li<sup>2</sup>, David Lilja<sup>2</sup>, Kia Bazargan<sup>3</sup>*

<sup>1</sup>University of Louisiana at Lafayette, <sup>2</sup>University of Minnesota, Twin Cities, <sup>3</sup>University of Minnesota

5:05PM

2C.5

**High-Performance NoCs employing the DSP48E1 blocks of the Xilinx FPGAs**

*Prabhu Prasad B M<sup>1</sup>, Khyamling parane<sup>2</sup>, Basavaraj Talawar<sup>3</sup>*

<sup>1</sup>National Institute of Technology Karnataka, Surathkal, <sup>2</sup>National Institute of Technology Karnataka, <sup>3</sup>CSE, NITK, Surathkal

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## SESSION 3A

Thursday March 7

### Deep Learning Circuits and Architectures

Chair: **Dr. Sicheng Li**, HPE

Co-Chair: **Pravin Kumar Venkatesan**, Velodyne LiDAR

10:00AM

#### 3A.1

##### **MReC: A Multilayer Photonic Reservoir Computing Architecture**

*Dharanidhar Dhang, Syed Ali Hasnain, Rabi Mahapatra*

Texas A&M University

10:20AM

#### 3A.2

##### **Dynamic Reconfiguration of CNNs for Input-Dependent Approximation**

*Maedeh Hemmat<sup>1</sup> and Azadeh Davoodi<sup>2</sup>*

<sup>1</sup>University of Wisconsin-Madison, <sup>2</sup>University of Wisconsin, Madison

10:40AM

#### 3A.3

##### **An Application Specific Processor Architecture with 3D Inetegration for Recurrent Neural Networks**

*Sumon Dey and Paul D. Franzon*

North Carolina State University

11:00AM

#### 3A.4

##### **Task-Based Neuromodulation Architecture for Lifelong Learning**

*Anurag Daram<sup>1</sup>, Dhireesha Kudithipudi<sup>1</sup>, Angel Yanguas-Gil<sup>2</sup>*

<sup>1</sup>Rochester Institute of Technology, <sup>2</sup>Argonne National Laboratory, Lemont

## SESSION 3B

Thursday March 7

### Innovations In Classic Hardware Security Problems

Chair: **Dr. Lin Yuan**, Amazon

Co-Chair: **Anupam Chattopadhyay**, Nanyang Technological University

10:00AM

#### 3B.1

##### **PUF-PassSE: A PUF based Password Strength Enhancer for IoT Applications**

*Qian Wang<sup>1</sup>, Mingze Gao<sup>2</sup>, Gang Qu<sup>3</sup>*

<sup>1</sup>University of Maryland, <sup>2</sup>University of Maryland, College Park, <sup>3</sup>Univ. of Maryland, College Park

10:20AM

#### 3B.2

##### **On SAT-Based Attacks On Encrypted Sequential Logic Circuits**

*Yasaswy Kasarabada, Suyuan Chen, Ranga Vemuri*

University of Cincinnati

10:40AM

#### 3B.3

##### **A Darwinian Genetic Algorithm for State Encoding Based Finite State Machine Watermarking**

*Matthew Lewandowski and Srinivas Katkoori*

University of South Florida

11:00AM

#### 3B.4

##### **Lightweight Secure-Boot Architecture for RISC-V System-on-Chip**

*Jawad Haj-Yahya<sup>1</sup>, Ming Ming Wong<sup>2</sup>, Vikramkumar Pudi<sup>3</sup>, Shivam Bhasin<sup>4</sup>, Anupam Chattopadhyay<sup>4</sup>*

<sup>1</sup>Agency for Science Technology and Research

(ASTAR), <sup>2</sup>Nanyang Technological University, <sup>3</sup>Indian Institute of Technology

Tirupati, <sup>4</sup>Nanyang Technological University



## SESSION 3C

Thursday March 7

### Co-Optimization of Device Performance and Design Reliability from State-of-the-art FinFET to Quantum Technologies

Chair: **Prof. Vita Hu**, National Central University, Taiwan

Co-Chair: **Aswin Mehta**, Texas Instruments

10:00AM

#### 3C.1

##### **VeriSFQ: A Semi-formal Verification Framework and Benchmark for Single Flux Quantum Technology**

*Alvin D. Wong<sup>1</sup>, Kevin Su<sup>1</sup>, Hang Sun<sup>1</sup>, Arash Fayyazi<sup>1</sup>, Massoud Pedram<sup>2</sup>, Shahin Nazarian<sup>1</sup>*

<sup>1</sup>University of Southern California, <sup>2</sup>USC

10:20AM

#### 3C.2

##### **Speed Optimization of Vertically Stacked Gate-All-Around MOSFETs with Inner Spacers for Low Power and Ultra-Low Power Applications**

*Ya-Chi Huang, Meng-Hsueh Chiang, Shui-Jinn Wang*

National Cheng Kung University

10:40AM

#### 3C.3

##### **Impact of Self-heating on Performance and Reliability in FinFET and GAAFET Designs**

*Vidya A. Chhabria and Sachin S. Sapatnekar*

University of Minnesota

11:00AM

#### 3C.4

##### **Device Designs and Analog Performance Analysis for Negative-Capacitance Vertical-Tunnel FET**

*Hung-Han Lin and Vita Pi-Ho Hu*

National Central University

## SESSION 4A

Thursday March 7

### Artificial Intelligence for Efficient Application Specific Hardware

Chair: **Dr. Amey Kulkarni**, Velodyne LiDAR

Co-Chair: **Dr. Abhilash Goyal**, Velodyne LiDAR

11:40AM

#### 4A.1

##### **Behavioral Modeling of Tunable I/O Drivers with Pre-emphasis Using Neural Networks**

*Huan Yu<sup>1</sup>, Jaemin Shin<sup>2</sup>, Tim Michalka<sup>2</sup>, Mourad Larbi<sup>1</sup>, Madhavan Swaminathan<sup>1</sup>*

<sup>1</sup>Georgia Institute of Technology, <sup>2</sup>Qualcomm Technologies, Inc.

12:00PM

#### 4A.2

##### **Small Memory Footprint Neural Network Accelerators**

*Kenshu Seto<sup>1</sup>, Hamid Nejatollahi<sup>2</sup>, Jiyoung An<sup>3</sup>, Sujin Kang<sup>4</sup>, Nikil Dutt<sup>2</sup>*

<sup>1</sup>Tokyo City University, <sup>2</sup>University of California, Irvine, <sup>3</sup>Kyung Hee University, <sup>4</sup>Hanyang University

12:20PM

#### 4A.3

##### **Minimizing Classification Energy of Binarized Neural Network Inference for Wearable Devices**

*Morteza Hosseini<sup>1</sup>, Hirenkumar Paneliya<sup>1</sup>, Utteja Panchakshara Kallakuri Niyogi<sup>2</sup>, mohit khatwani<sup>2</sup>, Tinoosh Mohsenin<sup>1</sup>*

<sup>1</sup>University of Maryland Baltimore County, <sup>2</sup>University of Maryland, Baltimore County

12:40PM

#### 4A.4

##### **Exploiting Energy-Accuracy Trade-off through Contextual Awareness in Multi-Stage Convolutional Neural Networks**

*Katayoun neshatpour, Farnaz Behnia, Houman Homayoun, Avesta Sasan*

George Mason University

## SESSION 4B

Thursday March 7

### Verification, ATPG and Failure Analysis

Chair: **Vinod Vishwanath**, Real Intent, Inc.

Co-Chair: **Sreejit Chakravarty**, Intel Corporation

11:40AM

#### 4B.1

##### **Assertion Coverage Aware Trace Signal Selection in Post-Silicon Validation**

*Xiaobang Liu and Ranga Vemuri*

University of Cincinnati

12:00PM

#### 4B.2

##### **A Communication-Centric Observability Selection for Post-Silicon System-on-Chip Integration Debug**

*Yuting Cao<sup>1</sup>, Hao Zheng<sup>1</sup>, Sandip Ray<sup>2</sup>*

<sup>1</sup>University of South Florida, <sup>2</sup>University of Florida

12:20PM

#### 4B.2

##### **Automatic Test Pattern Generation for Double Stuck-at Faults Based on Test Patterns of Single Faults**

*Peikun Wang<sup>1</sup>, Amir Masoud Gharehbaghi<sup>2</sup>, Masahiro Fujita<sup>1</sup>*

<sup>1</sup>University of Tokyo, <sup>2</sup>The University of Tokyo

12:40PM

#### 4B.2

##### **Deep Learning-Based Wafer-Map Failure Pattern Recognition Framework**

*Tsutomu Ishida, Izumi Nitta, Daisuke Fukuda, Yuzi Kanazawa*

Fujitsu Laboratories Ltd.

## SESSION 5A

Thursday March 7

### Physical Design Optimization

Chair: **Rung-Bin Lin**, Yuan Ze University

Co-Chair: **Srinivas Katkoori**, University of South Florida

3:40PM

#### 5A.1

##### **Drive-Strength Selection for Synthesis of Leakage-Dominant Circuits**

*Mahfuzul Islam<sup>1</sup>, Shinichi Nishizawa<sup>2</sup>, Yusuke Matsui<sup>3</sup>, Yoshinobu Ichida<sup>3</sup>*

<sup>1</sup>Kyoto University, <sup>2</sup>Saitama University, <sup>3</sup>ROHM Semiconductor

4:00PM

#### 5A.2

##### **Estimating Pareto Optimum Fronts to Determine Knob Settings in Electronic Design Automation Tools**

*Billy Huggins, W. Rhett Davis, Paul Franzon*

North Carolina State University

4:20PM

#### 5A.3

##### **An Artificial Intelligence Approach to EDA Software Testing: Application to Net Delay Algorithms in FPGAs**

*Madhu Raman, Nizar Abdallah, Julien Dunoyer*

Microsemi

4:40PM

#### 5A.4

##### **Impact of Double-Row Height Standard Cells on Placement and Routing**

*Rung-Bin Lin and Yu-Xiang Chiang*

Yuan Ze University

## **SESSION 5B.1**

**Thursday March 7**

### **3D Integration & Advanced Packaging**

Chair: **Ali A. Shahi**, GlobalFoundries

Co-Chair: **Vinod Vishwanath**, Real Intent, Inc.

*3:40PM*

#### **5B.1.1**

**A Non-Slicing 3-D Floorplan Representation for Monolithic 3-D IC Design**

*Shantonu Das and Dae Hyun Kim*

Washington State University

*4:00PM*

#### **5B.1.2**

**Routing Complexity Minimization of Monolithic Three-Dimensional Integrated Circuits**

*Sheng-En(David) Lin and Dae Hyun Kim*

Washington State University

## SESSION 5B.2

Thursday March 7

### Future of SOC Architectures and Verification

Chair: **Vinod Vishwanath**, Real Intent, Inc.

Co-Chair: **Ali A. Shahi**, GlobalFoundries

*4:20PM*

#### **5B.2.1**

**Towards Energy Efficient non-von Neumann Architectures for Deep Learning**

*Antara Ganguly<sup>1</sup>, Rajeev Muralidhar<sup>2</sup>, Virendra Singh<sup>1</sup>*

<sup>1</sup>Indian Institute of Technology, Bombay, <sup>2</sup>Telstra Communications

*4:40PM*

#### **5B.2.2**

**Closing the Verification Gap with Static Sign-off**

*Pranav Ashar and Vinod Viswanath*

Real Intent, Inc.

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